MITSUBISHI ELECTRIC
Changes for the Better

TO:	ME-UK	**DATE:**	28/10/2016
	ME-Italy, ME-RUS	**FROM:**	MEU Mktg / Eng
	ME-France		SZ, MG
	ME-CE	**DEPT.:**	SEMI
CC:	MK, WH, HN, BK, BU, JN, ST, SB, IL, DC, SR, TGH, JL, MG, SZ		

PRODUCT DISCONTINUATION NOTIFICATION

PDN number :	**PDN - H - 03 - 16**

Herewith we want to inform you about the product discontinuation for the following device:

a) Mitsubishi type number (device family):	some SiRF devices (listed in the attached Excel) (selected **RA**xxxxxxx-xxx and **RD**xxxxx-xxx).
b) Old Mitsubishi type number:	RA-modules and RA-transistors with suffixes -100, -101, -201, -T113, -T212, -T214, -T1105. Detailed type numbers see attached Excel list.
c) New Mitsubishi type number:	Partly replaced by new modules / transistors. Partly no direct replacement. New suffixes are: -500, -501, -501, -T513, -T512, -T514, -T5105. Detailed type numbers see attached Excel list.
d) Expected last order for discontinued device:	**30. June 2017 (Last Time Buy)**
e) Date of production stop:	**31. March 2018 (Last Shipment)**
f) Customer spec. /part number:	All suffixes included
g) Remarks:	Affected type numbers see attached Excel list. This PDN is caused by the discontinuation of the Renesas Kochi Silicon chip factory. A new chip supplier was selected and qualified.

(Signature of responsible Manager)

Note: Please comment until 25. November 2016. Otherwise we regard the PDN as accepted.

Date October 28th, 2016
G2K-R-161024-12

to MEU customers

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Miyoshi Electronics Corporation

Reliability test plan for New fab Devices

	Package Type	Tested Model Number	Issue date of Reliability Test Report	Test item
Module	H2M	RA60H3847M1	Jan. 2017	High temperature storage Low temperature storage Humidity storage Temperature cycling
Discrete	SLP	RD07MUS2B	Nov. 2016	Resistance to Soldering heat (Pre-treatment) High temperature storage Low temperature storage Humidity storage Temperature cycling
	SOT89	RD02LUS2	Feb. 2017	Resistance to Soldering heat (Pre-treatment) High temperature storage Low temperature storage Humidity storage Temperature cycling
	PMM	RD07MUP2B	Feb. 2017	Resistance to Soldering heat (Pre-treatment) High temperature storage Low temperature storage Humidity storage Temperature cycling
	HPM	RD35HUF2	Dec. 2016	Resistance to Soldering heat (Pre-treatment) High temperature storage Low temperature storage Humidity storage Temperature cycling
	HPM2	RD35HUP2	Dec. 2016	Resistance to Soldering heat (Pre-treatment) High temperature storage Low temperature storage Humidity storage Temperature cycling
	TO220	RD16HHF1	Aug. 2017	High temperature storage Low temperature storage Humidity storage Temperature cycling
	Ceramic	RD100HHF1C	Mar. 2017	High temperature storage Low temperature storage Humidity storage Temperature cycling